



6 4-15-03 PM  
2822

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kazuaki Ano

Docket No.: TI-33183

Serial No.: 10/017,737

Examiner: Lewis, Monica

Filed: 12/14/2001

Art Unit: 2822

For: Wirebonded Multichip Module

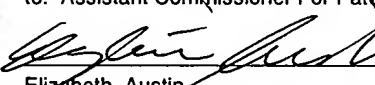
Conf. No.: 8828

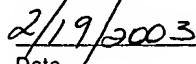
TRANSMITTAL OF FORMAL DRAWINGS

Assistant Commissioner For Patents  
Attn: Official Drafts Person  
Washington, DC 20231

MAILING CERTIFICATE UNDER 37 C.F.R. § 1.8(a)

I hereby certify that the above correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner For Patents, Washington, DC 20231.

  
Elizabeth Austin

  
Date  
2/19/2003

Dear Sir:

Submitted herewith is 1 sheet of formal drawings.

The enclosed drawings are being provided in a timely manner therefore no additional fee is required.

Respectfully submitted,



Michael K. Skrehot  
Attorney for Applicant  
Reg. No.: 36,682

Texas Instruments Incorporated  
P. O. Box 655474, MS 3999  
Dallas, Texas 75265  
(972) 917-5653

RECEIVED  
FEB 26 2003  
200 MAIL ROOM